

01/10/02

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10043468	FILING DATE 01/10/2002	CLASS 438	SUBCLASS	GAU 2823	EXAMINER
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\*\*APPLICANTS: Farnsworth Warren;

\*\*CONTINUING DATA VERIFIED:

THIS APPLICATION IS A CON OF 09/478,386 01/06/2000  
WHICH IS A DIV OF 09/304,368 05/04/1999 PAT 6,204,095  
WHICH IS A CON OF 09/056,124 04/06/1998 PAT 5,933,713

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\*\* FOREIGN APPLICATIONS VERIFIED:

PC-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 3085.4US (96-1033.4)
Verified and Acknowledged Examiner's initials		
TITLE : Method of forming overmolded chip scale package and resulting product		
U.S. DEPT. OF COMM./PAT. & TM-PTO-438 (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
Amount Due	Date Paid		Total Claims	Print Claim for O.G
ISSUE FEE		Primary Examiner	DRAWING	
			Sheets Drwg.	Figs. Drwg.
TERMINAL		Application Examiner		
DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.		

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